

Title (en)

Alkaline plating baths & electroplating process.

Title (de)

Alkalische Plattierungsbäder und Verfahren zum Elektroplattieren.

Title (fr)

Bains de placage alcalins et procédé de dépôt électrolytique.

Publication

EP 0101769 A1 19840307 (EN)

Application

EP 82304561 A 19820831

Priority

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Abstract (en)

Cyanide-free plating baths for the electrodeposition of copper and zinc alloys comprise aqueous alkaline mixtures which contain copper and zinc ions and a chelating agent selected from glucoheptonic acid and its salts. Processes for electroplating using the bath and for removing the metal ions from the spent baths by pH adjustment are also disclosed.

IPC 1-7

C25D 3/56; **C25D 3/58**

IPC 8 full level

C25D 3/56 (2006.01); **C25D 3/58** (2006.01)

CPC (source: EP)

C25D 3/565 (2013.01); **C25D 3/58** (2013.01)

Citation (search report)

- [A] US 3642591 A 19720215 - BOOSE CESAR ADRIANUS, et al
- [A] US 3219560 A 19651123 - PETER LEENDERS, et al
- [A] DE 2635560 A1 19771117 - ROQUETTE FRERES

Designated contracting state (EPC)

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DOCDB simple family (publication)

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